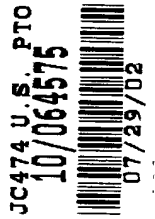


Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID:	16725	
Application ID:	10064575	
Title of Invention:	BUMP LAYOUT ON SILICON CHIP	
First Named Inventor:	Wen-Chih Yang	
Domestic/Foreign Application:	Domestic Application	
Filing Date:	null	
Effective Receipt Date:	2002-07-29	
Submission Type:	Utility Patent Filing	
Filing Type:	new-utility	
Confirmation Number:	0	
Attorney Docket Number:	7808-US-PA	
Digital Certificate Holder:	cn=Belinda Lee, ou=Registered Attorneys, ou=Patent and Trademark Office, ou=Department of Commerce, o=U.S. Government, c=US	
Certificate Message Digest:	VrHnsD2Mu/gBdRXY1QWxAA==	
Total Fees Authorized:	\$780.0	
Payment Category:	CC - Credit Card	
Credit Card Number:	*****3109	
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RAM Accounting Date:	2002-07-29	
RAM Sequence Number:	494480	
RAM Payment Status:	RAM success	
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TRANSMITTAL FORM



Electronic Version 1.0.3

Stylesheet Version: 1.0

Attorney Docket
Number:7808-US-
PASubmission Type: Utility Patent
Filing

BUMP LAYOUT ON SILICON CHIP

First Named Inventor: Mr. Wen-Chih Yang

SUBMITTED BY

Name:	Dr. BELINDA LEE
Registration Number:	46,863
Electronic Signature Mark: /Belinda Lee/	Date Signed: 20020729

I certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.

I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.

Attached Files:

declaration	7808declaration1.tif
declaration	7808declaration2.tif
specification	7808usf.xml
patent-assignments	7808usasgn.xml
fee-transmittal	7808usfee.xml

bibd-transmittal

7808usapds.xml

Attached Image File(s):

7808declaration1.tif

7808declaration2.tif

Comments:

COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

BUMP LAYOUT ON SILICON CHIP

the specification of which

X is attached hereto.

_____ was filed on _____

as Application Serial No. _____ and was amended on _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):

Number	Country	Date Filed(yyyy/mm/dd)	Yes	No
90119108	Taiwan, R.O.C.	2001/8/6	X	

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

Belinda Lee	(Reg. No. 46,863)	Marrina Mei	(Reg. No. 44,935)
Jiawei Huang	(Reg. No. 43,330)		
Charles C.H. Wu	(Reg. No. 39,081)		

SEND CORRESPONDENCE TO:

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JIANQ CHYUN Intellectual Property Office
7F.-1, No. 100, Roosevelt Rd., Sec. 2,
Taipei 100, Taiwan, R.O.C.
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Belinda Lee

FEE TRANSMITTAL

Electronic Version 1.1.0

Stylesheet Version: 1.0

Patent fees are subject to annual revisions on or about October 1st of each year.

Large Entity

TOTAL FEES AUTHORIZED: \$ 780

BANK (CREDIT) CARD INFORMATION:

Credit Card Number: 3109
 Expiration Date: 20030430
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BASIC FILING FEE

Fee Description	Fee Code	Fee Paid
Utility Filing Fee	101	\$ 740

Subtotal For Basic Filing Fee: \$ 740

EXTRA CLAIM FEES

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 13	103	\$ 18	0	\$ 0
Independent Claims: 2	102	\$ 84	0	\$ 0

Subtotal For Extra Claims Fees: \$ 0

ADDITIONAL FEES

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Recording Each Patent Assignment Per Property Fee	00000000	1	581	\$ 40	\$ 40

Subtotal For Additional Fees: \$ 40